What's New - July 2023

Article

ThinkEdge SE350 V2 and SE360 V2 servers

The ThinkEdge SE350 V2 and SE360 V2 are new compute and storage server designed specifically to meet the needs of remote locations.

The SE350 V2 is a 1U height, half-width, and short-depth edge server, designed to operate in high temperatures as well as with tolerance to locations with high-dust and vibration. The server supports 4x 7mm hot-swap drives for data redundancy and ease of maintenance, and offers a full suite of physical and electronic security measures to keep data safe.

Figure 1. ThinkEdge SE350 V2

The SE360 V2 is a 2U height, half-width, and short-depth Edge server with large storage capacity, both hot-swap and internal. With support for up to two NVIDIA A2 GPUs planned, the SE360 V2 is designed to virtualize traditional IT and OT applications as well as new transformative Edge AI systems. The SE360 V2 also offers a full suite of physical and electronic security measures to keep customer data safe.

Figure 2. ThinkEdge SE360 V2 (shown with wireless antennas, planned for 4Q/2023)

Both servers support the Intel® Xeon® D-2700 processor with support for up to 256GB of high-performance 3200 MHz DDR4 memory.

For more information about the SE350 V2 see the following resources:

- SE350 V2 datasheet
- SE350 V2 3D Tour
- SE350 V2 product guide
- SE350 V2 product web page

For more information about the SE360 V2 see the following resources:

- SE360 V2 datasheet
- SE360 V2 3D Tour
- SE360 V2 product guide
- SE360 V2 product web page

Also check these portfolio resources that have been updated to include the edge servers:

- Servers and Storage Portfolio Guide
- Server comparison

ThinkSystem DG Series storage

The ThinkSystem DG Series All-Flash QLC storage systems are built on high-density NVMe QLC flash technology, making them ideal for non-latency-sensitive deployments with a small storage footprint — including data lakes, backup consolidation, or transitioning from hybrid/HDD to all-flash storage. Reduce your data center costs with a more sustainable and more efficient solution than hybrid flash and HDD systems.

Learn about the new ThinkSystem DG5000 and ThinkSystem DG7000 with the ThinkSystem DG Series datasheet.

Learn about our new data management solutions that include the new ThinkSystem DG and the rest of our storage portfolio, delivering faster time-to-insight, simplifying business operations, and maximizing data resiliency from edge to cloud.

Figure 3. ThinkSystem DG Series All-Flash QLC Array

ThinkSystem DM3010H storage array

Lenovo ThinkSystem DM3010H is a unified, hybrid storage system that is designed to provide performance, simplicity, capacity, security, and high availability for small enterprises and remote offices/branch offices of large enterprises. Powered by the ONTAP software, ThinkSystem DM3010H delivers enterprise-class storage management capabilities with a wide choice of host connectivity options, flexible drive configurations, and enhanced data management features. The DM3010H is the follow-on to the DM3000H offering improved performance, including 32Gb connectivity and the support of 4x 25GbE cluster interconnects.

Learn more about the DM3010H and the other ThinkSystem DM Hybrid offerings with the ThinkSystem DM Series Hybrid Flash datasheet.

The DM3010H will be orderable in the configurator in August.

Figure 4. The ThinkSystem DM3010H is the follow-on to the DM3000H

ThinkSystem SR950 V3

The Lenovo ThinkSystem SR950 V3 is an 8-socket 8U server that offers technology advances, including eight 4th Gen Intel Xeon Scalable processors, up to 32TB of 4800 MHz DDR5 memory, and PCIe 5.0 slots and drives.

The SR950 V3 is designed for the most demanding, mission-critical workloads, such as in-memory databases, large transactional databases, real-time analytics, ERP, CRM, and virtualized server workloads.

Learn more about the server with these documents and web pages:

- Datasheet
- Product Guide
- Product web page

Also check these portfolio resources that have been updated to include the SR950 V3:

- Servers and Storage Portfolio Guide
- Server comparison

Figure 5. Lenovo ThinkSystem SR950 V3

Support for Front PCIe slots on 1U and 2U AMD servers

The following servers now support front PCIe slots:

- ThinkSystem SR665 V3 - 2U2S AMD server
- ThinkSystem SR465 V3 - 1U2S AMD server
- ThinkSystem SR655 V3 - 2U1S AMD server
- ThinkSystem SR635 V3 - 1U1S AMD server

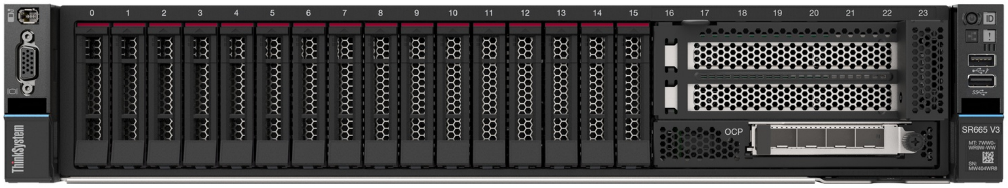

Figure 6. The ThinkSystem SR665 V3 (and similarly, the SR655 V3) with front PCIe slots

Figure 7. The ThinkSystem SR645 V3 (and similarly, the SR635 V3) with front PCIe slots

The support of front slots means that customers can deploy servers with all drives and adapter at the front of the server, thereby reducing the need for IT support personnel to work in the rear of the server (hot-aisle), which has the potential of reducing infrastructure costs. Some server configurations alternatively support both front and rear slots, enabling more adapters to be installed in the servers.

Learn more in the updated product guides:

- SR665 V3 product guide
- SR645 V3 product guide
- SR655 V3 product guide
- SR635 V3 product guide

Tip: Look for front PCIe slot support in the SR650 V3 and SR630 V3, coming in August.

New drives for ThinkSystem servers

In July, we announced the following drive families:

- ThinkSystem PM9A3 Read Intensive NVMe PCIe 4.0 SSDs
    - 960GB, 1.92TB and 3.84TB capacities
    - 2.5-inch hot swap, 7mm hot-swap, 7mm trayless, and M.2 form factors
- ThinkSystem M.2 ER2 Read Intensive SATA 6Gb SSDs
    - Only announced for customers in China

These drives are announced in most ThinkSystem V2 servers. Additional server support is planned.

Figure 8. ThinkSystem PM9A3 Read Intensive NVMe SSDs (2.5-inch trayless form factor shown)

New drives for ThinkSystem storage

In July, we announced the following drives for our Thinksystem DE storage arrays:

- 22TB 3.5-inch (LFF) drives
- 2.4TB 2.5-inch (SFF) drives including a FIPS drive

For details, see the ThinkSystem DE product guides:
https://lenovopress.lenovo.com/storage/thinksystem/de-series#rt=product-guide

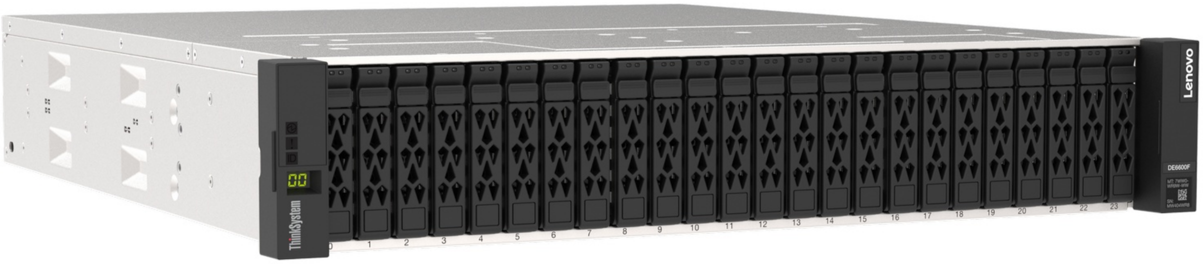

Figure 9. ThinkSystem DE6600H with 2.5-inch drive bays

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